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FSAM50SM60A

Motion SPM® 2 Series

Features

- UL Certified No. E209204 (UL1557)
- 600 V - 50 A 3-Phase IGBT Inverter with Integral Gate Drivers and Protection
- Low-Loss, Short-Circuit Rated IGBTs
- Very Low Thermal Resistance Using Al₂O₃ DBC Substrate
- Separate Open-Emitter Pins from Low Side IGBTs for Three-Phase Current Sensing
- Single-Grounded Power Supply
- Optimized for 5 kHz Switching Frequency
- Built-in NTC Thermistor for Temperature Monitoring
- Inverter Power Rating of 4.0 kW / 100~253 VAC
- Adjustable Current Protection Level via Selection of Sense-IGBT Emitter's External Rs
- Isolation Rating: 2500 V_{rms} / min.

Applications

- Motion Control - Home Appliance / Industrial Motor

Resource

- [AN-9043 - Motion SPM® 2 Series User's Guide](#)

General Description

FSAM50SM60A is a Motion SPM® 2 module providing a fully-featured, high-performance inverter stage for AC Induction, BLDC, and PMSM motors. These modules integrate optimized gate drive of the built-in IGBTs to minimize EMI and losses, while also providing multiple on-module protection features including under-voltage lockouts, over-current shutdown, thermal monitoring, and fault reporting. The built-in, high-speed HVIC requires only a single supply voltage and translates the incoming logic-level gate inputs to the high-voltage, high-current drive signals required to properly drive the module's internal IGBTs. Separate negative IGBT terminals are available for each phase to support the widest variety of control algorithms.

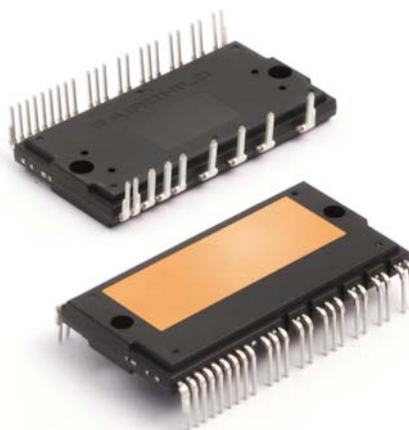


Figure 1. Package Overview

Package Marking and Ordering Information

| Device | Device Marking | Package | Packing Type | Quantity |
|-------------|----------------|-----------|--------------|----------|
| FSAM50SM60A | FSAM50SM60A | S32CA-032 | Rail | 8 |

Integrated Power Functions

- 600V - 50 A IGBT inverter for three-phase DC / AC power conversion (please refer to Figure 3)

Integrated Drive, Protection and System Control Functions

- For inverter high-side IGBTs: gate drive circuit, high-voltage isolated high-speed level shifting control circuit Under-Voltage Lock-Out (UVLO) Protection
Note) Available bootstrap circuit example is given in Figures 13 and 14.
- For inverter low-side IGBTs: gate drive circuit, Short-Circuit Protection (SCP) control supply circuit Under-Voltage Lock-Out (UVLO) Protection
- Temperature Monitoring: system temperature monitoring using built-in thermistor
Note) Available temperature monitoring circuit is given in Figure 14.
- Fault signaling: corresponding to a SC fault (low-side IGBTs) and UV fault (low-side control supply)
- Input interface: active-LOW Interface, works with 3.3 / 5 V logic, Schmitt-trigger input

Pin Configuration

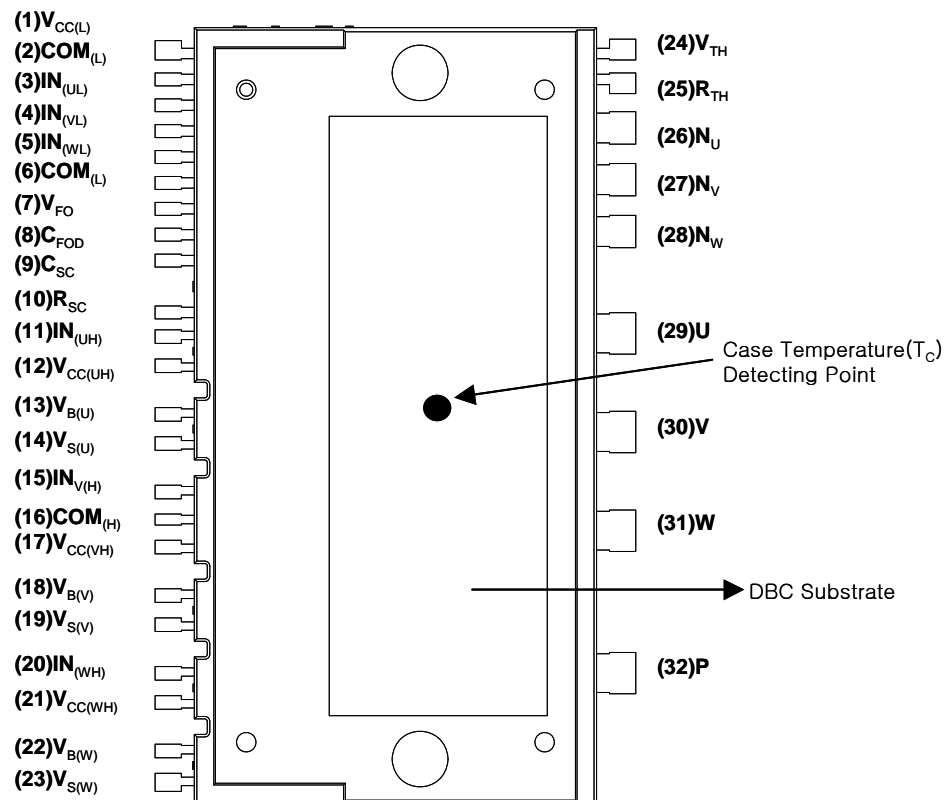


Figure 2. Top View

Pin Descriptions

| Pin Number | Pin Name | Pin Description |
|------------|--------------|---|
| 1 | $V_{CC(L)}$ | Low-Side Common Bias Voltage for IC and IGBTs Driving |
| 2 | $COM_{(L)}$ | Low-Side Common Supply Ground |
| 3 | $IN_{(UL)}$ | Signal Input Terminal for Low-Side U-Phase |
| 4 | $IN_{(VL)}$ | Signal Input Terminal for Low-Side V-Phase |
| 5 | $IN_{(WL)}$ | Signal Input Terminal for Low-Side W-Phase |
| 6 | $COM_{(L)}$ | Low-Side Common Supply Ground |
| 7 | V_{FO} | Fault Output |
| 8 | C_{FOD} | Capacitor for Fault Output Duration Selection |
| 9 | C_{SC} | Capacitor (Low-Pass Filter) for Short-Circuit Current Detection Input |
| 10 | R_{SC} | Resistor for Short-Circuit Current Detection |
| 11 | $IN_{(UH)}$ | Signal Input for High-Side U-Phase |
| 12 | $V_{CC(UH)}$ | High-Side Bias Voltage for U-Phase IC |
| 13 | $V_{B(U)}$ | High-Side Bias Voltage for U-Phase IGBT Driving |
| 14 | $V_{S(U)}$ | High-Side Bias Voltage Ground for U-Phase IGBT Driving |
| 15 | $IN_{(VH)}$ | Signal Input for High-Side V-Phase |
| 16 | $COM_{(H)}$ | High-Side Common Supply Ground |
| 17 | $V_{CC(VH)}$ | High-Side Bias Voltage for V-Phase IC |
| 18 | $V_{B(V)}$ | High-Side Bias Voltage for V-Phase IGBT Driving |
| 19 | $V_{S(V)}$ | High-Side Bias Voltage Ground for V-Phase IGBT Driving |
| 20 | $IN_{(WH)}$ | Signal Input for High-side W-Phase |
| 21 | $V_{CC(WH)}$ | High-Side Bias Voltage for W-Phase IC |
| 22 | $V_{B(W)}$ | High-Side Bias Voltage for W-Phase IGBT Driving |
| 23 | $V_{S(W)}$ | High-Side Bias Voltage Ground for W-Phase IGBT Driving |
| 24 | V_{TH} | Thermistor Bias Voltage |
| 25 | R_{TH} | Series Resistor for the Use of Thermistor (Temperature Detection) |
| 26 | N_U | Negative DC-Link Input Terminal for U-Phase |
| 27 | N_V | Negative DC-Link Input Terminal for V-Phase |
| 28 | N_W | Negative DC-Link Input Terminal for W-Phase |
| 29 | U | Output for U-Phase |
| 30 | V | Output for V-Phase |
| 31 | W | Output for W-Phase |
| 32 | P | Positive DC-Link Input |

Internal Equivalent Circuit and Input/Output Pins

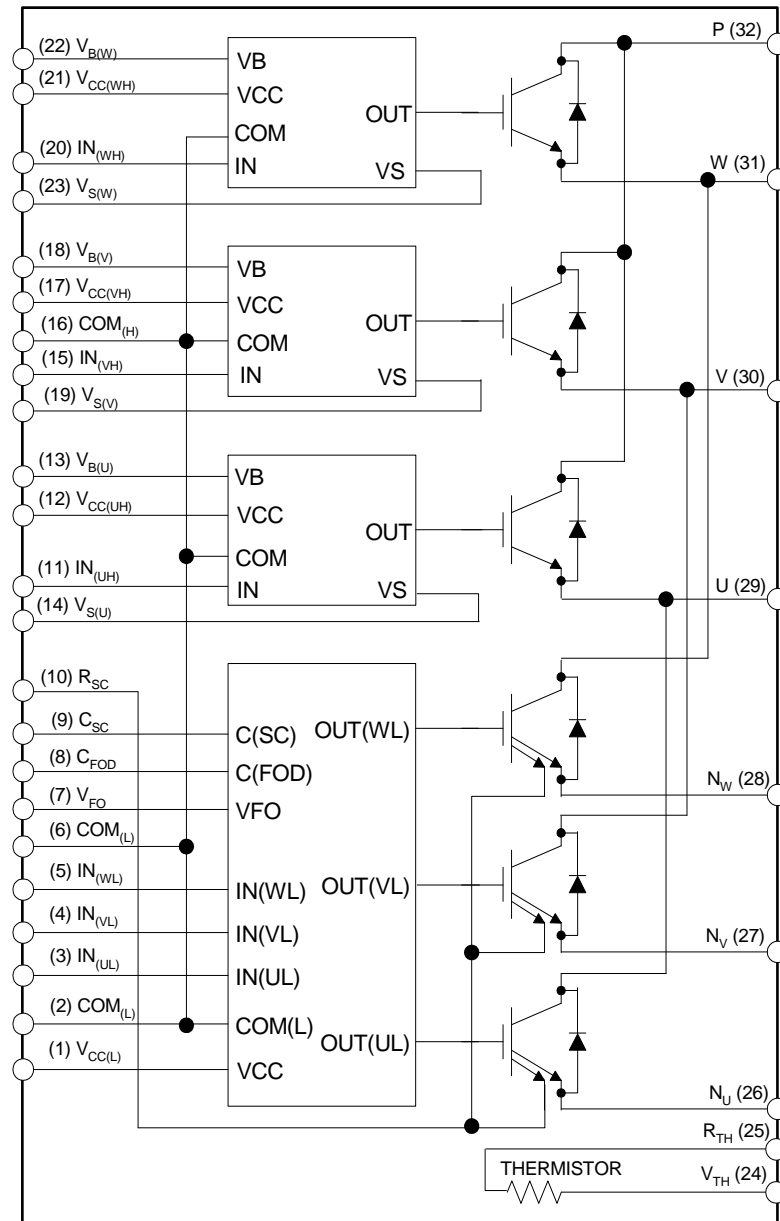


Figure 3. Internal Block Diagram

1st Notes:

1. Inverter low-side is composed of three sense-IGBTs including freewheeling diodes for each IGBT and one control IC which has gate driving, current-sensing and protection functions.
2. Inverter power side is composed of four inverter DC-link input pins and three inverter output pins.
3. Inverter high-side is composed of three normal-IGBTs including freewheeling diodes and three drive ICs for each IGBT.

Absolute Maximum Ratings ($T_J = 25^\circ\text{C}$, unless otherwise specified.)**Inverter Part**

| Item | Symbol | Condition | Rating | Unit |
|------------------------------------|------------------------|--|-----------|------------------|
| Supply Voltage | V_{DC} | Applied to DC-Link | 450 | V |
| Supply Voltage (Surge) | $V_{PN(\text{Surge})}$ | Applied between P and N | 500 | V |
| Collector - Emitter Voltage | V_{CES} | | 600 | V |
| Each IGBT Collector Current | $\pm I_C$ | $T_C = 25^\circ\text{C}$ | 50 | A |
| Each IGBT Collector Current | $\pm I_C$ | $T_C = 100^\circ\text{C}$ | 25 | A |
| Each IGBT Collector Current (Peak) | $\pm I_{CP}$ | $T_C = 25^\circ\text{C}$, Under 1ms Pulse Width | 100 | A |
| Collector Dissipation | P_C | $T_C = 25^\circ\text{C}$ per Chip | 100 | W |
| Operating Junction Temperature | T_J | (2nd Note 1) | -20 ~ 125 | $^\circ\text{C}$ |

2nd Notes:

1. It would be recommended that the average junction temperature should be limited to $T_J \leq 125^\circ\text{C}$ (at $T_C \leq 100^\circ\text{C}$) in order to guarantee safe operation.

Control Part

| Item | Symbol | Condition | Rating | Unit |
|--------------------------------|----------|---|---------------------|------|
| Control Supply Voltage | V_{CC} | Applied between $V_{CC(UH)}$, $V_{CC(VH)}$, $V_{CC(WH)}$ - $COM_{(H)}$, $V_{CC(L)}$ - $COM_{(L)}$ | 20 | V |
| High-Side Control Bias Voltage | V_{BS} | Applied between $V_{B(U)} - V_{S(U)}$, $V_{B(V)} - V_{S(V)}$, $V_{B(W)} - V_{S(W)}$ | 20 | V |
| Input Signal Voltage | V_{IN} | Applied between $IN_{(UH)}$, $IN_{(VH)}$, $IN_{(WH)}$ - $COM_{(H)}$, $IN_{(UL)}$, $IN_{(VL)}$, $IN_{(WL)}$ - $COM_{(L)}$ | -0.3 ~ $V_{CC}+0.3$ | V |
| Fault Output Supply Voltage | V_{FO} | Applied between V_{FO} - $COM_{(L)}$ | -0.3 ~ $V_{CC}+0.3$ | V |
| Fault Output Current | I_{FO} | Sink Current at V_{FO} Pin | 5 | mA |
| Current-Sensing Input Voltage | V_{SC} | Applied between C_{SC} - $COM_{(L)}$ | -0.3 ~ $V_{CC}+0.3$ | V |

Total System

| Item | Symbol | Condition | Rating | Unit |
|--|-----------------------|--|-----------|------------------|
| Self-Protection Supply Voltage Limit (Short-Circuit Protection Capability) | $V_{PN(\text{PROT})}$ | Applied to DC-Link, $V_{CC} = V_{BS} = 13.5 \sim 16.5 \text{ V}$, $T_J = 125^\circ\text{C}$, Non-Repetitive, $< 5 \mu\text{s}$ | 400 | V |
| Module Case Operation Temperature | T_C | See Figure 2 | -20 ~ 100 | $^\circ\text{C}$ |
| Storage Temperature | T_{STG} | | -20 ~ 125 | $^\circ\text{C}$ |
| Isolation Voltage | V_{ISO} | 60Hz, Sinusoidal, AC 1 Minute, Connect Pins to Heat Sink Plate | 2500 | V_{rms} |

Thermal Resistance

| Item | Symbol | Condition | Min. | Typ. | Max. | Unit |
|-------------------------------------|----------------|---|------|------|------|--------------------|
| Junction to Case Thermal Resistance | $R_{th(j-c)Q}$ | Inverter IGBT Part (per 1/6 module) | - | - | 1.00 | $^\circ\text{C/W}$ |
| | $R_{th(j-c)F}$ | Inverter FWDi Part (per 1/6 module) | - | - | 1.50 | $^\circ\text{C/W}$ |
| Contact Thermal Resistance | $R_{th(c-f)}$ | DBC Substrate (per 1 Module) Thermal Grease Applied (2nd Note 3) | - | - | 0.06 | $^\circ\text{C/W}$ |

2nd Notes:

2. For the measurement point of case temperature(T_C), please refer to Figure 2.
 3. The thickness of thermal grease should not be more than 100 μm .

Electrical Characteristics

Inverter Part ($T_J = 25^\circ\text{C}$, unless otherwise specified.)

| Item | Symbol | Condition | Min. | Typ. | Max. | Unit |
|--|---------------|--|------|------|------|---------------|
| Collector - emitter Saturation Voltage | $V_{CE(SAT)}$ | $V_{CC} = V_{BS} = 15\text{ V}$ $V_{IN} = 0\text{ V}$ $I_C = 50\text{ A}, T_J = 25^\circ\text{C}$ | - | - | 2.4 | V |
| FWDi Forward Voltage | V_{FM} | $V_{IN} = 5\text{ V}$ $I_C = 50\text{ A}, T_J = 25^\circ\text{C}$ | - | - | 2.1 | V |
| Switching Times | t_{ON} | $V_{PN} = 300\text{ V}, V_{CC} = V_{BS} = 15\text{ V}$ $I_C = 50\text{ A}, T_J = 25^\circ\text{C}$ $V_{IN} = 5\text{ V} \leftrightarrow 0\text{ V}$, Inductive Load (High- And Low-Side) (2nd Note 4) | - | 0.69 | - | μs |
| | $t_{C(ON)}$ | | - | 0.32 | - | μs |
| | t_{OFF} | | - | 1.32 | - | μs |
| | $t_{C(OFF)}$ | | - | 0.46 | - | μs |
| | t_{rr} | | - | 0.10 | - | μs |
| Collector-Emitter Leakage Current | I_{CES} | $V_{CE} = V_{CES}, T_J = 25^\circ\text{C}$ | - | - | 250 | μA |

2nd Notes:

4. t_{ON} and t_{OFF} include the propagation delay time of the internal drive IC. $t_{C(ON)}$ and $t_{C(OFF)}$ are the switching time of IGBT itself under the given gate driving condition internally. For the detailed information, please see Figure 4.

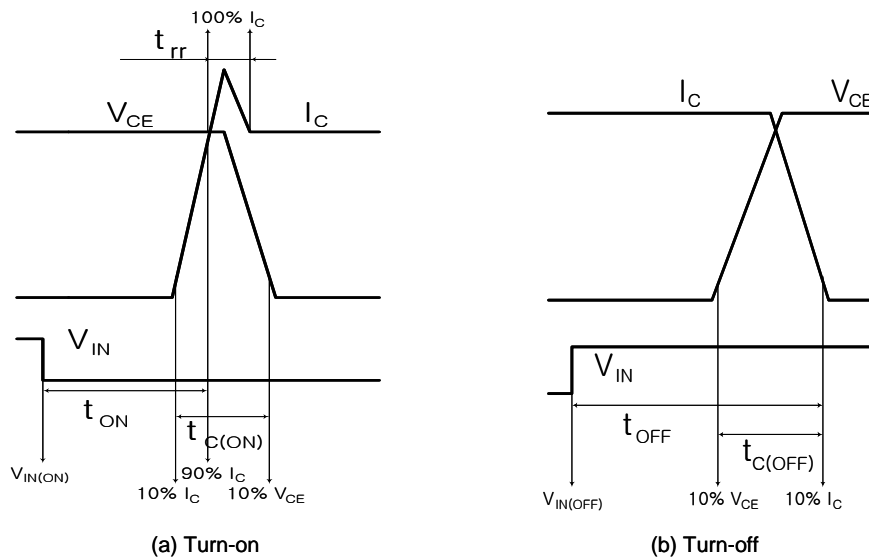


Figure 4. Switching Time Definition

Electrical Characteristics (T_J = 25°C, unless otherwise specified.)

Control Part

| Item | Symbol | Condition | Min. | Typ. | Max. | Unit |
|--|----------------------|--|------|------|------|------|
| Quiescent V _{CC} Supply Current | I _{QCCL} | V _{CC} = 15 V IN _(UL, VL, WL) = 5V | - | - | 26 | mA |
| | I _{QCCH} | V _{CC} = 15 V IN _(UH, VH, WH) = 5V | - | - | 130 | μA |
| Quiescent V _{BS} Supply Current | I _{QBS} | V _{BS} = 15 V IN _(UH, VH, WH) = 5V | - | - | 420 | μA |
| Fault Output Voltage | V _{FOH} | V _{SC} = 0 V, V _{FO} Circuit: 4.7 kΩ to 5 V Pull-up | 4.5 | - | - | V |
| | V _{FOL} | V _{SC} = 1 V, V _{FO} Circuit: 4.7 kΩ to 5 V Pull-up | - | - | 1.1 | V |
| Short-Circuit Trip Level | V _{SC(ref)} | V _{CC} = 15 V (2nd Note 5) | 0.45 | 0.51 | 0.56 | V |
| Sensing Voltage of IGBT Current | V _{SEN} | R _{SC} = 40 Ω, R _{SU} = R _{SV} = R _{SW} = 0 Ω and I _C = 75 A (See a Figure 6) | 0.45 | 0.51 | 0.56 | V |
| Supply Circuit Under-Voltage Protection | UV _{CCD} | Detection Level | 11.5 | 12.0 | 12.5 | V |
| | UV _{CCR} | Reset Level | 12.0 | 12.5 | 13.0 | V |
| | UV _{BSD} | Detection Level | 7.3 | 9.0 | 10.8 | V |
| | UV _{BSR} | Reset Level | 8.6 | 10.3 | 12.0 | V |
| Fault Output Pulse Width | t _{FOD} | C _{FOD} = 33 nF (2nd Note 6) | 1.4 | 1.8 | 2.0 | ms |
| ON Threshold Voltage | V _{IN(ON)} | High-Side Applied between IN _(UH) , IN _(VH) , IN _(WH) - COM _(H) | - | - | 0.8 | V |
| OFF Threshold Voltage | V _{IN(OFF)} | | 3.0 | - | - | V |
| ON Threshold Voltage | V _{IN(ON)} | Low-Side Applied between IN _(UL) , IN _(VL) , IN _(WL) - COM _(L) | - | - | 0.8 | V |
| OFF Threshold Voltage | V _{IN(OFF)} | | 3.0 | - | - | V |
| Resistance of Thermistor | R _{TH} | @ T _{TH} = 25°C (2nd Note 7, Figure 5) | - | 50 | - | kΩ |
| | | @ T _{TH} = 100°C (2nd Note 7, Figure 5) | - | 3.0 | - | kΩ |

2nd Notes:

- Short-circuit protection is functioning only at the low-sides. It would be recommended that the value of the external sensing resistor (R_{SC}) should be selected around 40 Ω in order to make the SC trip-level of about 75A, at the shunt resistors (R_{SU}, R_{SV}, R_{SW}) of 0 Ω. For the detailed information about the relationship between the external sensing resistor (R_{SC}) and the shunt resistors (R_{SU}, R_{SV}, R_{SW}), please see Figure 6.
- The fault-out pulse width t_{FOD} depends on the capacitance value of C_{FOD} according to the following approximate equation: C_{FOD} = 18.3 × 10⁻⁶ × t_{FOD} [F]
- T_{TH} is the temperature of thermistor itself. To know case temperature (T_C), please make the experiment considering your application.

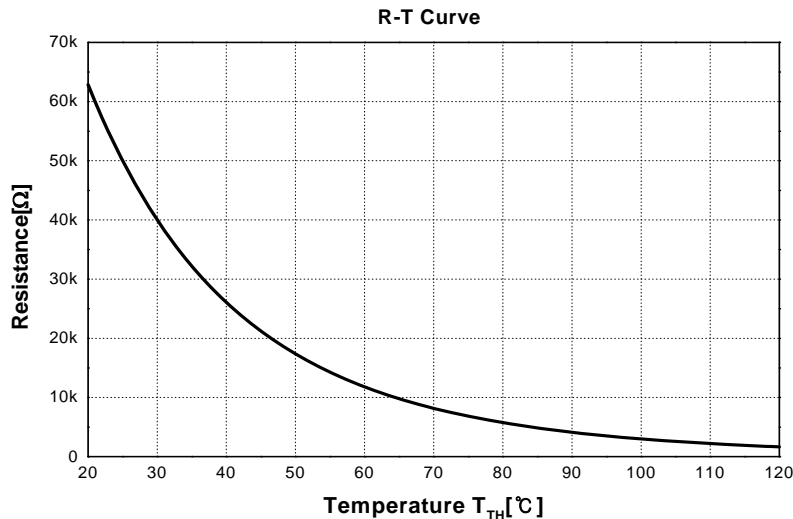


Figure 5. R-T Curve of The Built-in Thermistor

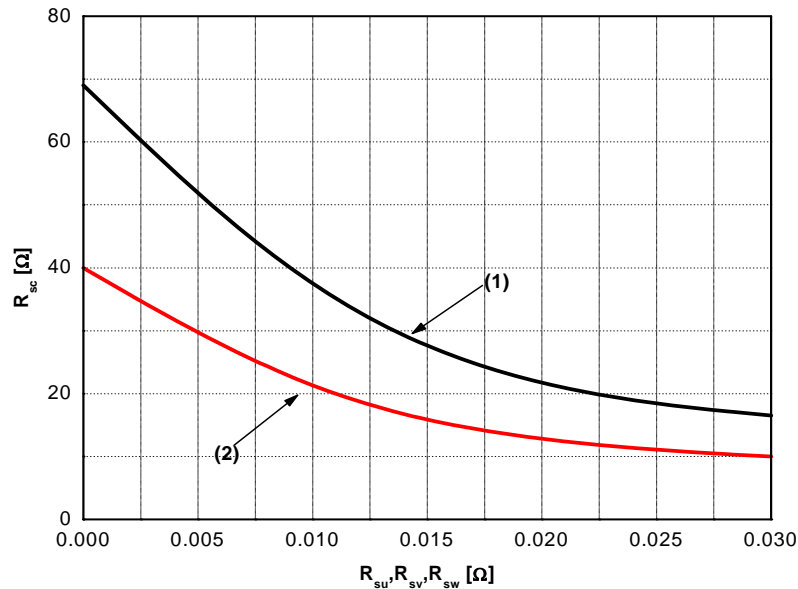


Figure 6. R_{SC} Variation by Change of Shunt Resistors (R_{SU} , R_{SV} , R_{SW}) for Short-Circuit Protection
 (1) @ Current Trip Level ≈ 50 A
 (2) @ Current Trip Level ≈ 75 A

Recommended Operating Conditions

| Item | Symbol | Condition | Min. | Typ. | Max. | Unit |
|--|----------------|---|----------|------|------|---------|
| Supply Voltage | V_{PN} | Applied between P - N_U , N_V , N_W | - | 300 | 400 | V |
| Control Supply Voltage | V_{CC} | Applied between $V_{CC(UH)}$, $V_{CC(VH)}$, $V_{CC(WH)}$ - $COM_{(H)}$, $V_{CC(L)}$ - $COM_{(L)}$ | 13.5 | 15.0 | 16.5 | V |
| High-side Bias Voltage | V_{BS} | Applied between $V_{B(U)}$ - $V_{S(U)}$, $V_{B(V)}$ - $V_{S(V)}$, $V_{B(W)}$ - $V_{S(W)}$ | 13.0 | 15.0 | 18.5 | V |
| Blanking Time for Preventing Arm-short | t_{dead} | For Each Input Signal | 3.5 | - | - | μ s |
| PWM Input Signal | f_{PWM} | $T_C \leq 100^\circ\text{C}$, $T_J \leq 125^\circ\text{C}$ | - | 5 | - | kHz |
| Minimum Input Pulse Width | $PW_{IN(OFF)}$ | $200 \leq V_{PN} \leq 400$ V, $13.5 \leq V_{CC} \leq 16.5$ V, $13.0 \leq V_{BS} \leq 18.5$ V, $0 \leq I_C \leq 100$ A, $-20 \leq T_J \leq 125^\circ\text{C}$ $V_{IN} = 5$ V \leftrightarrow 0 V, Inductive Load (2nd Note 8) | 3 | - | - | μ s |
| Input ON Threshold Voltage | $V_{IN(ON)}$ | Applied between $IN_{(UH)}$, $IN_{(VH)}$, $IN_{(WH)}$ - $COM_{(H)}$, $IN_{(UL)}$, $IN_{(VL)}$, $IN_{(WL)}$ - $COM_{(L)}$ | 0 ~ 0.65 | | | V |
| Input OFF Threshold Voltage | $V_{IN(OFF)}$ | Applied between $IN_{(UH)}$, $IN_{(VH)}$, $IN_{(WH)}$ - $COM_{(H)}$, $IN_{(UL)}$, $IN_{(VL)}$, $IN_{(WL)}$ - $COM_{(L)}$ | 4 ~ 5.5 | | | V |

2nd Notes:

8. Motion SPM® 2 product might not make response if the $PW_{IN(OFF)}$ is less than the recommended minimum value.

Mechanical Characteristics and Ratings

| Item | Condition | | Min. | Typ. | Max. | Units |
|-----------------|---|----------------------|------|------|------|-------|
| Mounting Torque | Mounting Screw: M4 (2nd Note 9 and 10) | Recommended 10 kg•cm | 8 | 10 | 12 | kg•cm |
| | | Recommended 0.98 N•m | 0.78 | 0.98 | 1.17 | N•m |
| DBC Flatness | | See Figure 7 | 0 | - | +120 | μm |
| Weight | | | - | 32 | - | g |

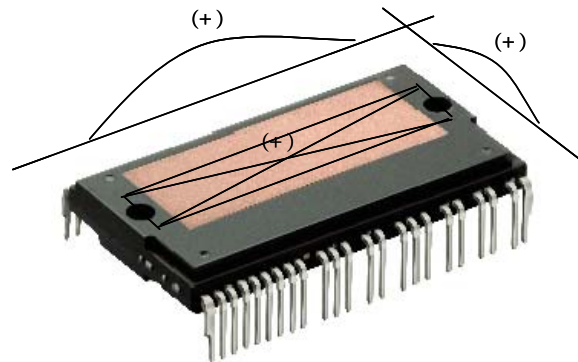


Figure 7. Flatness Measurement Position of The DBC Substrate

2nd Notes:

9. Do not make over torque or mounting screws. Much mounting torque may cause DBC substrate cracks and bolts and Al heat-sink destruction.
 10. Avoid one side tightening stress. Figure 8 shows the recommended torque order for mounting screws. Uneven mounting can cause the Motion SPM® 2 package DBC substrate to be damaged.

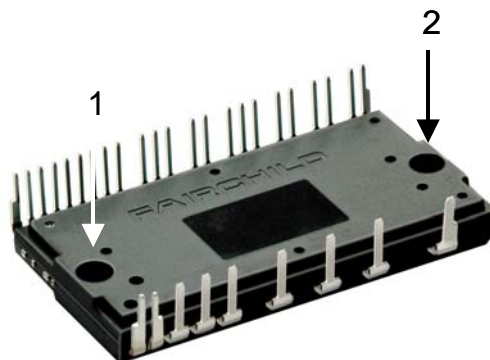
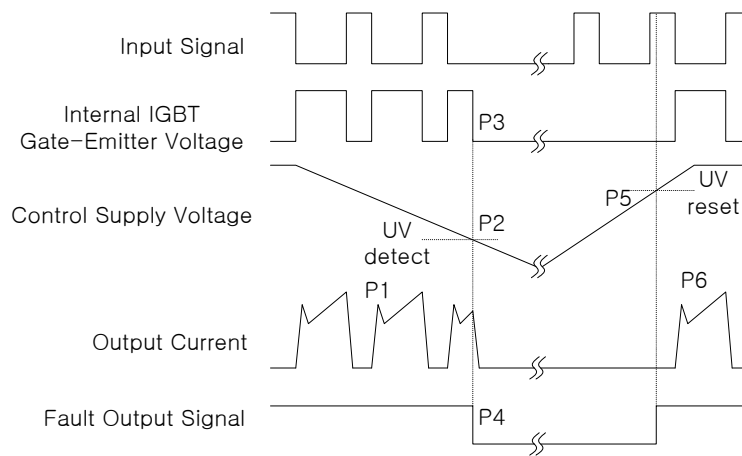


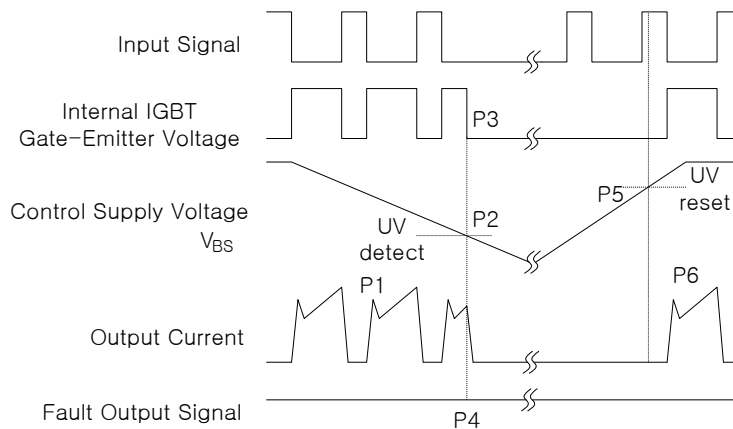
Figure 8. Mounting Screws Torque Order (1 → 2)

Time Charts of Protective Function



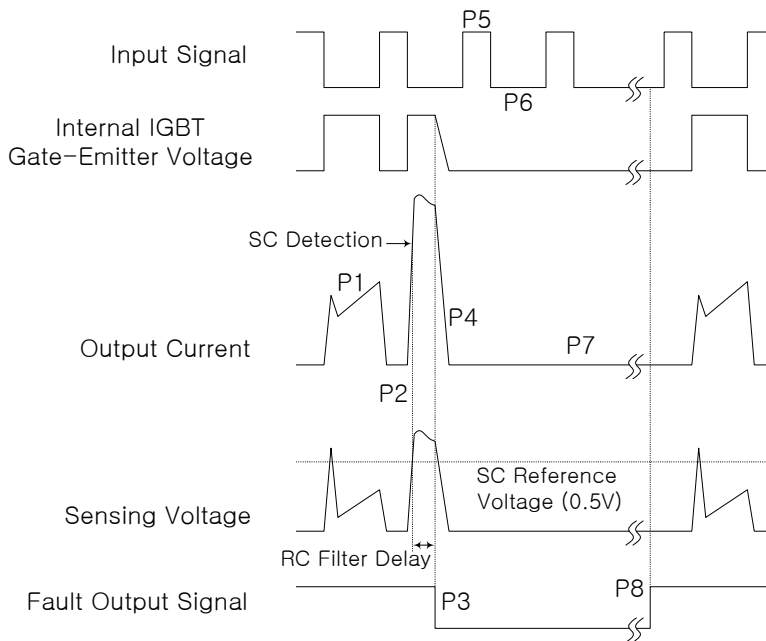
- P1 : Normal operation: IGBT ON and conducting current .
P2 : Under-voltage detection.
P3 : IGBT gate interrupt.
P4 : Fault signal generation.
P5 : Under-voltage reset.
P6 : Normal operation: IGBT ON and conducting current.

Figure 9. Under-Voltage Protection (Low-Side)



- P1 : Normal operation: IGBT ON and conducting current.
P2 : Under-voltage detection.
P3 : IGBT gate interrupt.
P4 : No fault signal.
P5 : Under-voltage reset.
P6 : Normal operation: IGBT ON and conducting current.

Figure 10. Under-Voltage Protection (High-Side)



- P1 : Normal operation: IGBT ON and conducting current.
P2 : Short-circuit current detection.
P3 : IGBT gate interrupt / fault signal generation.
P4 : IGBT is slowly turned off.
P5 : IGBT OFF signal.
P6 : IGBT ON signal: but IGBT cannot be turned on during the fault-output activation.
P7 : IGBT OFF state.
P8 : Fault-output reset and normal operation start.

Figure 11. Short-Circuit Protection (Low-Side Operation Only)

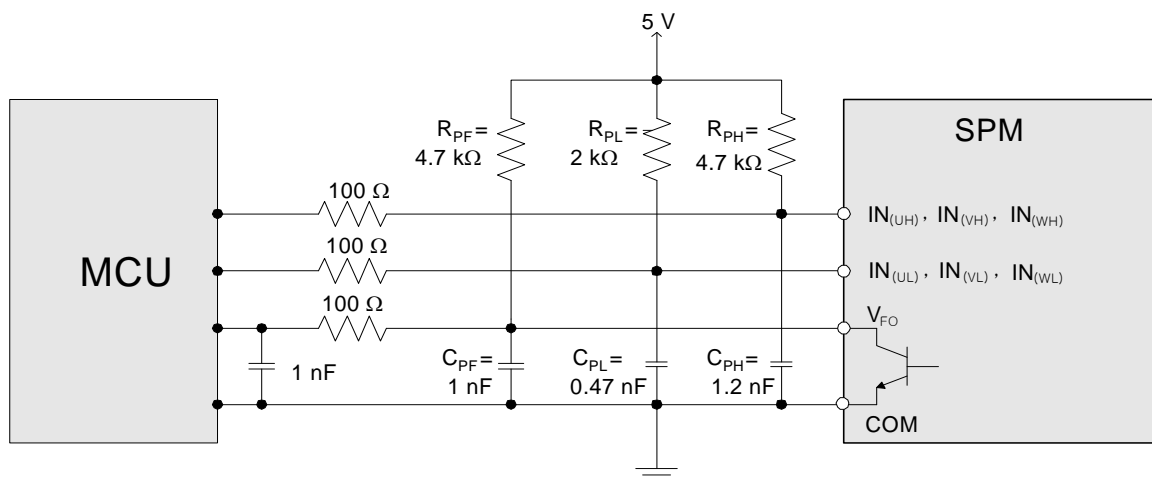


Figure 12. Recommended MCU I/O Interface Circuit

3rd Notes:

1. It would be recommended that by-pass capacitors for the gating input signals, $IN_{(UL)}$, $IN_{(VL)}$, $IN_{(WL)}$, $IN_{(UH)}$, $IN_{(VH)}$ and $IN_{(WH)}$ should be placed on the Motion SPM® 2 product pins and on the both sides of MCU and Motion SPM 2 Product for the fault output signal, V_{FO} , as close as possible.
2. The logic input works with standard CMOS or LSTTL outputs.
3. $R_{PL}C_{PL}/R_{PH}C_{PH}/R_{PF}C_{PF}$ coupling at each Motion SPM 2 product input is recommended in order to prevent input/output signals' oscillation and it should be as close as possible to each of Motion SPM 2 Product pins.

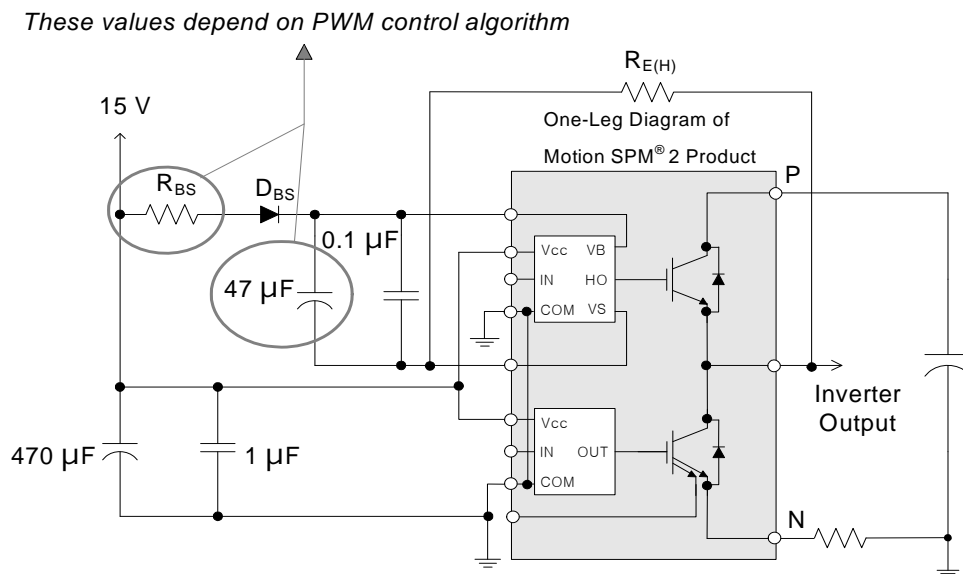
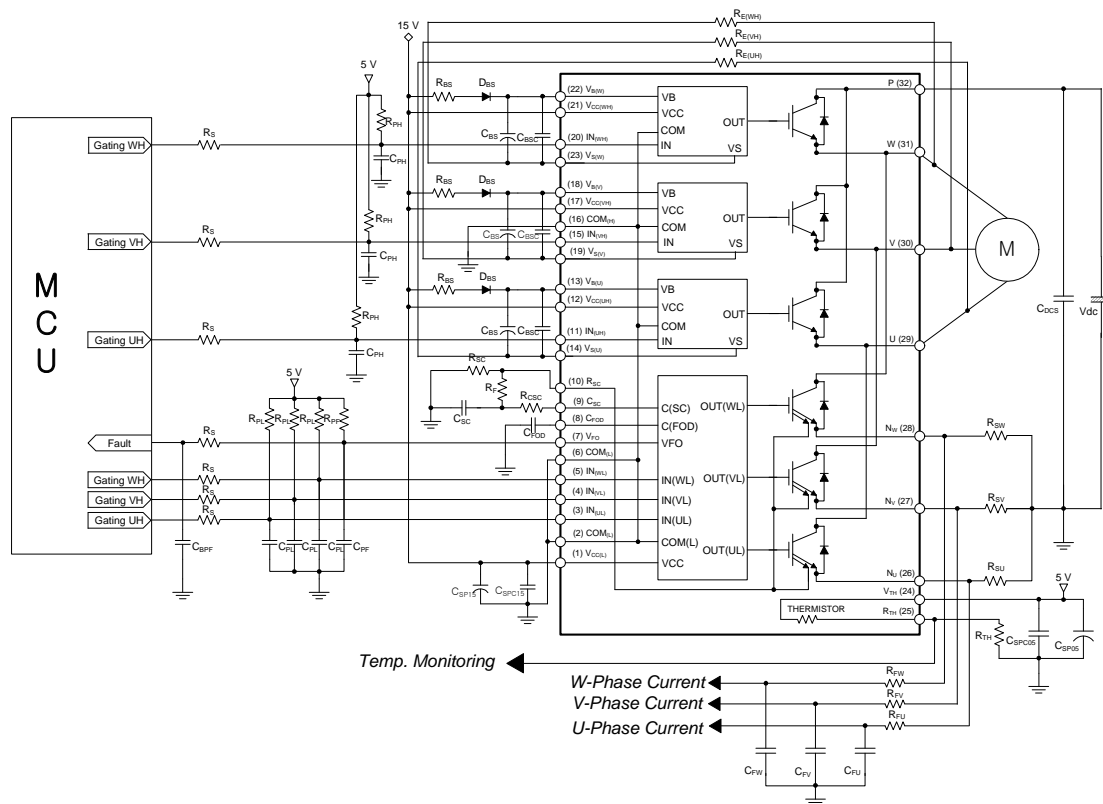
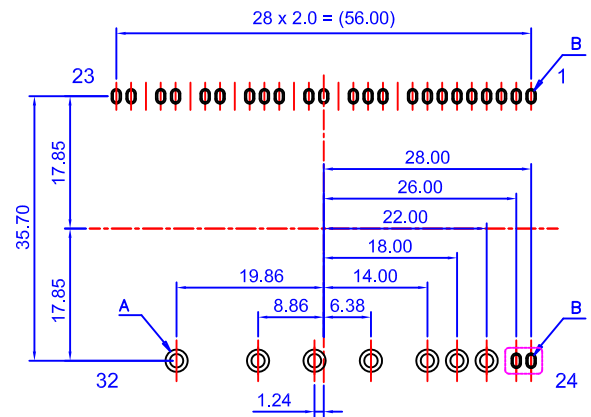
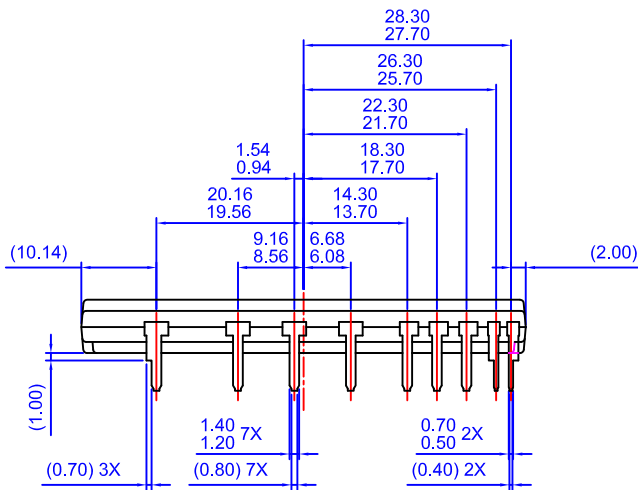
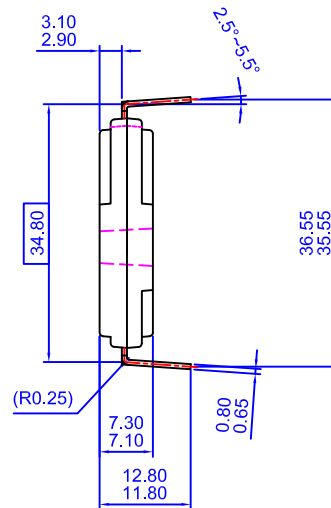
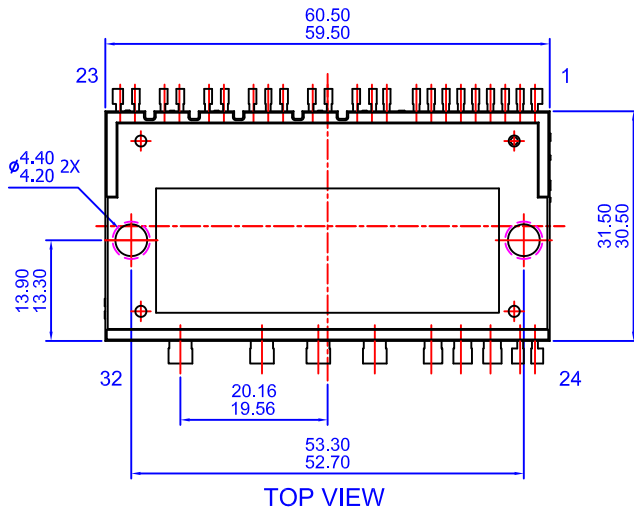
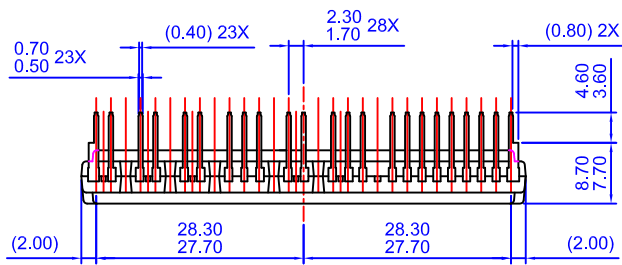


Figure 13. Recommended Bootstrap Operation Circuit and Parameters

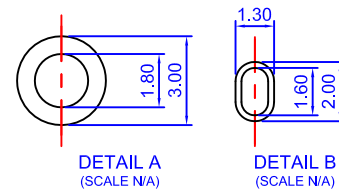
3rd Notes:

4. It would be recommended that the bootstrap diode, D_{BS} , has soft and fast recovery characteristics.
5. The bootstrap resistor (R_{BS}) should be three times greater than $R_{E(H)}$. The recommended value of $R_{E(H)}$ is 5.6Ω , but it can be increased up to 20Ω for a slower dv/dt of high-side.
6. The ceramic capacitor placed between V_{CC} - COM should be over $1\mu F$ and mounted as close to the pins of the Motion SPM® 2 product as possible.





- NOTES: UNLESS OTHERWISE SPECIFIED
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